



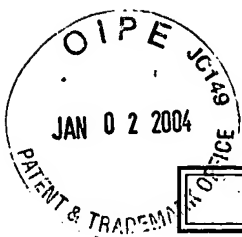
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Electronic Patent Application Submission
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Application ID: 10669820
Title of Invention: REINFORCED DIE PAD SUPPORT
STRUCTURE
First Named Inventor: Chung Tzu
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Filing Date: 2003-09-24
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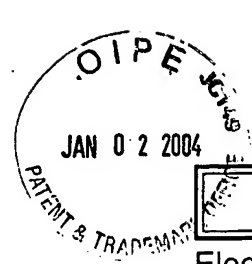
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Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	REINFORCED DIE PAD SUPPORT STRUCTURE									
<p>Application Number: 10/669820 </p> <p>Date: 2003-09-24</p> <p>First Named Applicant: Chung Hsing Tzu</p> <p>Confirmation Number: 5197</p> <p>Attorney Docket Number: AMKOR090A</p>										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids5-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids5-usidst.xml		us-ids.dtd		us-ids.xsl
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	us-ids.dtd									
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Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of
Invention

REINFORCED DIE PAD SUPPORT STRUCTURE

Application Number: 10/669820



Confirmation Number: 5197

First Named Applicant: Chung Tzu

Attorney Docket Number: AMKOR090A

Art Unit: 2811

Search string: (6197615 or 6198171 or 6201186 or 6201292
or 6204554 or 6208020 or 6208021 or 6208023
or 6211462 or 6218731 or 6222258 or 6225146
or 6229200 or 6229205 or 6239367 or 6239384
or 6242281 or 6256200 or 6258629 or 6281566
or 6281568 or 6282095 or 6285075 or 6291271
or 6291273 or 6294100 or 6294830 or 6295977
or 6297548 or 6303984 or 6303997 or 6307272
or 6309909 or 6316822 or 6316838 or 6323550
or 6326243 or 6326244 or 6326678 or 6335564
or 6337510 or 6339255 or 6348726 or 6355502
or 6369447 or 6369454 or 6373127 or 6380048
or 6384472 or 6388336).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6197615	2001-03-06	SONG ET AL			
	2	6198171	2001-03-06	HUANG ET AL			
	3	6201186	2001-03-13	DANIELS ET AL			
	4	6201292	2001-03-13	YAGI ET AL			
	5	6204554	2001-03-20	EWER ET AL			
	6	6208020	2001-03-27	MINAMIO			
	7	6208021	2001-03-27	OHUCHI ET AL			
	8	6208023	2001-03-27	NAKAYAMA ET AL			
	9	6211462	2001-04-03	CARTER, JR. ET AL			
	10	6218731	2001-04-17	HUANG ET AL.			

	11	6222258	2001-04-24	ASANO ET AL
	12	6225146	2001-05-01	YAMAGUCHI ET AL
	13	6229200	2001-05-08	MCLELLAN ET AL
	14	6229205	2001-05-08	JEONG ET AL
	15	6239367	2001-05-29	HSUAN ET AL.
	16	6239384	2001-05-29	SMITH ET AL
	17	6242281	2001-06-05	MCLELLAN ET AL
	18	6256200	2001-07-03	LAM ET AL
	19	6258629	2001-07-10	NIONES ET AL
	20	6281566	2001-08-28	MAGNI
	21	6281568	2001-08-28	GLENN ET AL.
	22	6282095	2001-08-28	HOUGHTON ET AL.
	23	6285075	2001-09-04	COMBS ET AL.
	24	6291271	2001-09-18	LEE ET AL.
	25	6291273	2001-09-18	MIYAKI ET AL.
	26	6294100	2001-09-25	FAN ET AL.
	27	6294830	2001-09-25	FJELSTAD
	28	6295977	2001-10-02	RIPPER ET AL.
	29	6297548	2001-10-02	MODEN ET AL.
	30	6303984	2001-10-16	CORISIS
	31	6303997	2001-10-16	LEE
	32	6307272	2001-10-23	TAKAHASHI ET AL.
	33	6309909	2001-10-30	OHGIYAMA
	34	6316822	2001-11-13	VENKATESHWARAN ET AL.
	35	6316838	2001-11-13	OZAWA ET AL.
	36	6323550	2001-11-27	MARTIN ET AL.
	37	6326243	2001-12-04	SUZUYA ET AL.
	38	6326244	2001-12-04	BROOKS ET AL.
	39	6326678	2001-12-04	KARMEZOS ET AL.
	40	6335564	2002-01-01	POUR
	41	6337510	2002-01-08	CHUN-JEN ET AL.
	42	6339255	2002-01-15	SHIN
	43	6348726	2002-02-19	BAYAN ET AL.
	44	6355502	2002-03-12	KANG ET AL.
	45	6369447	2002-04-09	MORI
	46	6369454	2002-04-09	CHUNG

	47	6373127	2002-04-16	BAUDOUIN ET AL.
	48	6380048	2002-04-30	BOON ET AL.
	49	6384472	2002-05-07	HUANG
	50	6388336	2002-05-14	VENKATESHWARAN ET AL.

Signature

Examiner Name	Date